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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2835  
Examiner: M. Datskovskiy

In Re PATENT APPLICATION OF:

Applicant: Seiji ANDOH

Serial No.: 09/376,063

Filed: August 17, 1999

For: PACKAGE STRUCTURE FOR A  
SEMICONDUCTOR DEVICE

Attorney Ref: OKI 226

AMENDMENT

May 13, 2002

Commissioner for Patents  
Washington, D.C. 20231  
**Box – Non-Final Office Action**

Sir:

This Amendment is filed in response to the Office Action dated December 13, 2001, the time for response to which is extended up to and including May 13, 2002, by the Petition for Extension of Time submitted here with. Please amend the above-referenced application as follows:

**IN THE SPECIFICATION:**

Please replace the paragraph on page 4, lines 20-26, with the following:

As shown in Fig. 2, the radiation solder bumps 13 are located in the central region of the back surface of the substrate 11a. Surrounding

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